Chapter D: CSP

D4. References

D4.1 Recommended Readings

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D4.3 Standards

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J-STD-020, Moisture/Reflow Sensitivity Classification of Plastic Surface Mount devices, October 1996.

Official representative proposal
J-STD-027, Mechanical Outline Standard for Flip Chip or Chip Scale Configurations
J-STD-028, Performance Standard for Flip Chip/Chip Scale Bumps
J-STD-029, Test Methods for Flip Chip or Chip Scale Products
J-STD-030, Qualification and Performance of Flip Chip Underfill Materials
J-STD-031, Mechanical Outline Standard for Ball Grid rays and other High Density Technology
J-STD-032, Performance Standard for Ball Grid Array Bumps and Columns

Working Draft
J-STD-033, Packaging and Handling of moisture Sensitive Non-Hermetic Solid State Surface Mount Devices
J-STD-035, Acoustic Microscopy for Non-Hermetic Encapsulated Electronic Components
IPC-7076, Sectional Requirements for Chip Scale and Chip Size Component Mounting

D4.4 Conferences

Surface Mount International: http://www.surfacemount.com
IPC National Conferences: http://www.ipc.org/html/framesetEAEexpo.html
SEMI Technical Proceedings: http://www.semi.org
NEPCON: http://nepcon.reedexpo.com
CHIPCON: http://www.semitech.com/chipcon/index.html
APCON: http://www.semitech.com/apcon/index.html

D4.5 Companies

Amkor/Anam: http://www.amkor.com/assembly_and_test/products/chipscale/index.htm
ChipScale Inc.: http://www.chipscale.com
Flip Chip technologies: http://www.flipchip.com/electron.htm
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Hitachi Cable: http://www.hitachi-cable.co.jp/microbga/index.htm
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